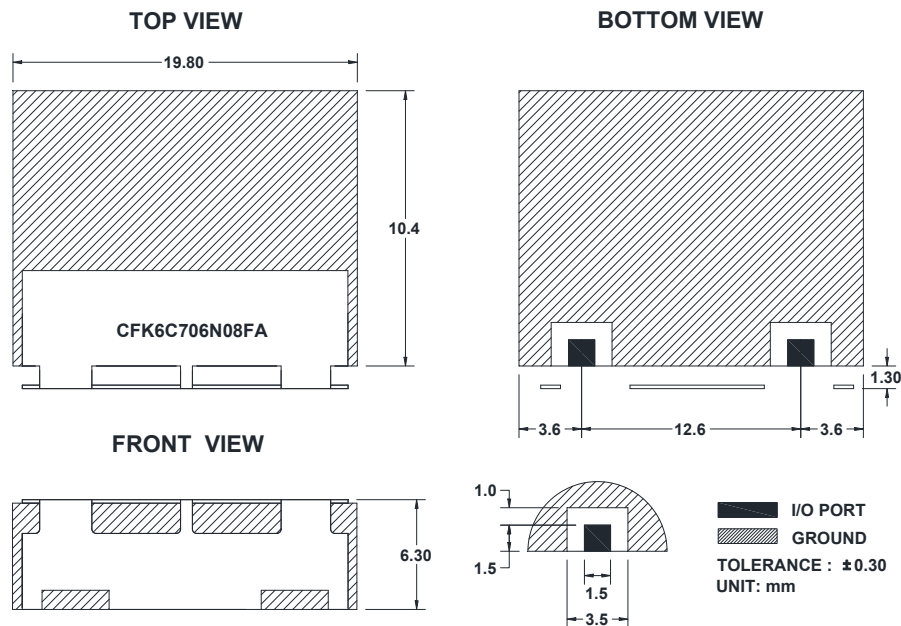


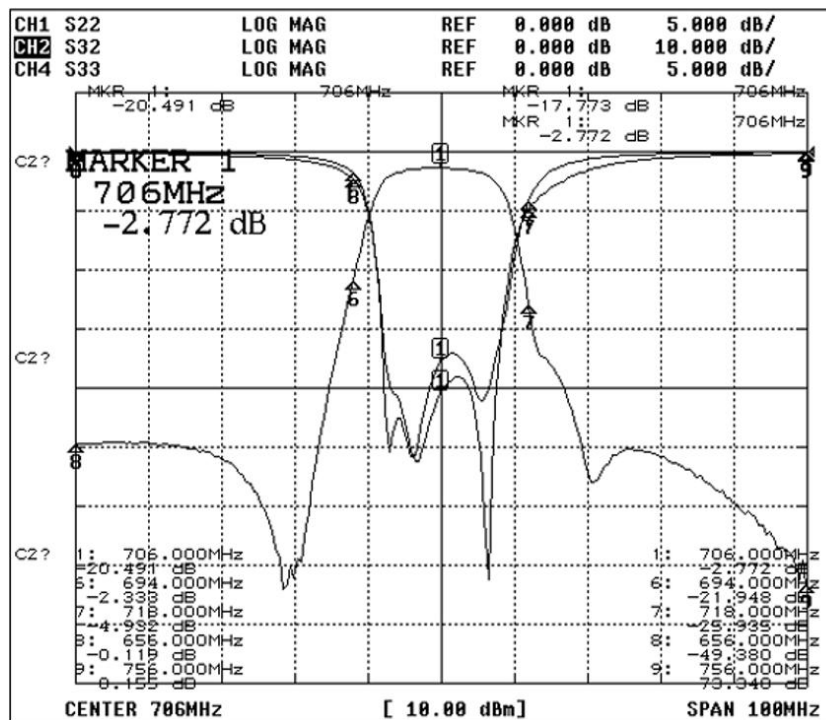
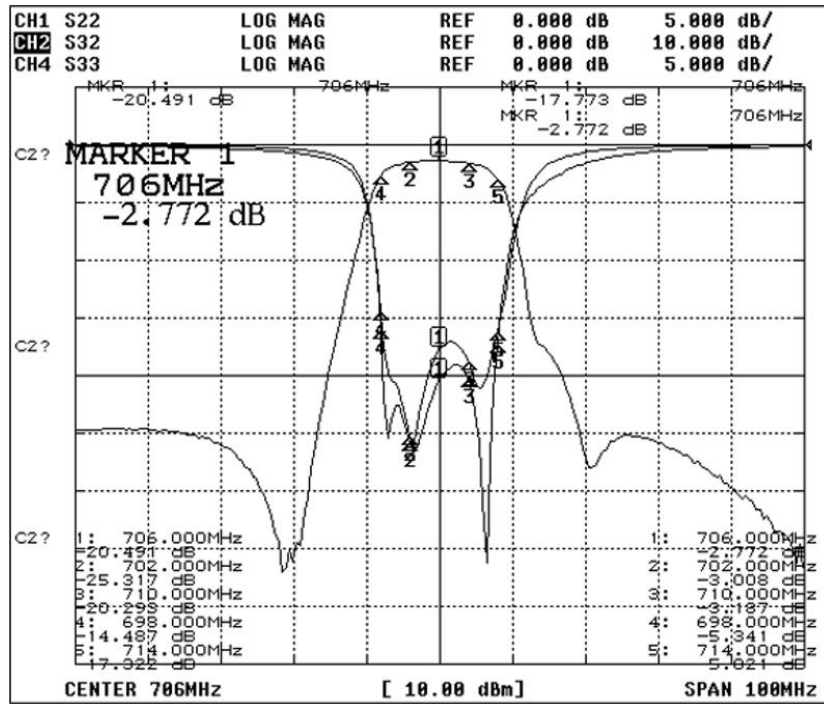
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	706.0	MHz
Bandwidth [BW]	$f_o \pm 4.0$ [702.0 ~ 710.0]	MHz
Insertion Loss in BW	3.5	dB max
Ripple in BW	0.8	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	5.0 dB min. @ $f_o \pm 8.0$ [698.0 & 714.0]	MHz
	20.0 dB min. @ $f_o \pm 12.0$ [694.0 & 718.0]	MHz
	40.0 dB min. @ $f_o \pm 50.0$ [656.0 & 756.0]	MHz
	dB min. @ $f_o \pm$ [&]	MHz
Group Delay Variation		ns max
Input Power	2.0	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

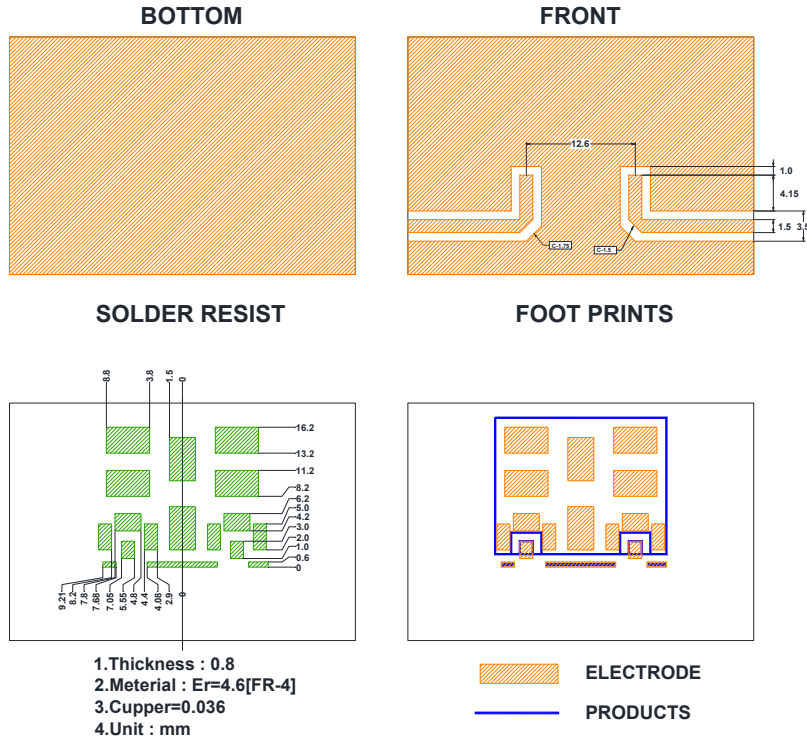
Mechanical Specification



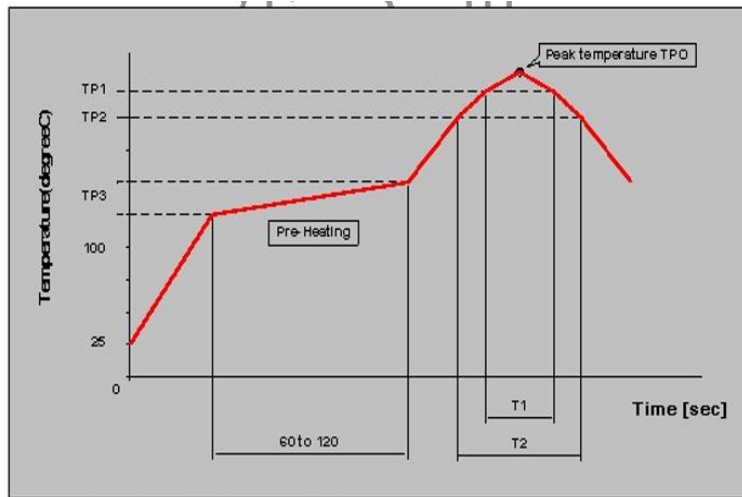
Plot Data



Recommended PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/-0	240	20	220	70	150 to 180